# **Product Preview**

# **Single D-Type Flip-Flop**

The NL17SZ374 is a single positive edge-triggered D-Type Flip-Flop in a tiny footprint package. The SC70-6/SC-88 occupies a very small board area. The device performs much as LCX multi-gate products in speed and drive.

- Tiny SC70-6/SC-88 Package
- TPD(MAX) < 5.0 nsecs at 3.0 Volts
- Source/Sink 24 mA at 3.0 Volts
- Over-Voltage Tolerant Inputs and Outputs
- Pin For Pin with NC7SZ374
- Chip Complexity: FETs = TBD

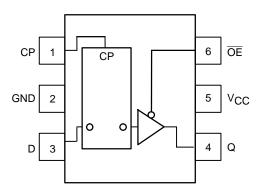


Figure 1. Pinout (Top View)

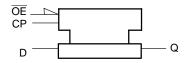


Figure 2. Logic Symbol

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#### MARKING DIAGRAMS



SC-88/SOT-363/SC70-6 DF SUFFIX CASE 419B



d = Date Code

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### **PIN ASSIGNMENT**

Pin	Function
D	Data Input
СР	Clock Pulse Input
ŌĒ	Output Enable Input
Q	Flip-Flop Output

#### **FUNCTION TABLE**

	Output		
СР	D	ŌĒ	Q
ſ	L	L	L
ſ	Н	L	Н
l	Х	L	Q <sub>n</sub>
Х	Х	Н	Z

H = HIGH Logic Level L = LOW Logic Level Z= High Impedance Q<sub>n</sub> = No Change in Data X = Immaterial

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

#### **MAXIMUM RATINGS**

Symbol		Parameter	Value	Unit
VCC	DC Supply Voltage		-0.5  to  +7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5  to  +7.0	V
Vout	DC Output Voltage		-0.5  to  +7.0	V
IK	DC Input Diode Current		-50	mA
IOK	DC Output Diode Current		-50	mA
lout	DC Output Sink Current		±50	mA
ICC	DC Supply Current per Supply Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case	for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta$ JA	Thermal Resistance	SC-70/SC-88A (Note 1) TSOP-5	350 230	°C/W
PD	Power Dissipation in Still Air at 85°C	SC-70/SC-88A TSOP-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >200 N/A	V
I <sub>Latch</sub> –Up	Latch-Up Performance	Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	UL 94 V-0 @ 0.125 in	

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- Tested to EIA/JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
VCC	DC Supply Voltage		2.0	5.5	V
V <sub>IN</sub>	DC Input Voltage		0	5.5	V
Vout	DC Output Voltage		0	5.5	V
TA	Operating Temperature Range		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$V_{CC} = 3.0 \text{ V } \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V } \pm 0.5 \text{ V}$	0 0	100 20	ns/V

# DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

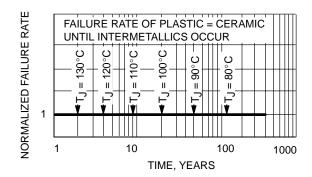


Figure 3. Failure Rate vs. Time Junction Temperature

#### DC ELECTRICAL CHARACTERISTICS

			VCC	ΤΔ	T <sub>A</sub> = 25°C		$-40^{\circ}\text{C} \leq \text{T}_{ extsf{A}} \leq 85^{\circ}\text{C}$		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
VIH	High-Level Input Voltage		2.3 to 5.5	0.7 V <sub>CC</sub>			0.7 V <sub>CC</sub>		V
VIL	Low-Level Input Voltage		2.3 to 5.5			0.3 V <sub>C</sub> C		0.3 V <sub>C</sub> C	V
VOH	High-Level Output Voltage	I <sub>OH</sub> = 100 μA	2.3 to 5.5	V <sub>CC</sub> - 0.1	VCC		V <sub>CC</sub> - 0.1		V
	$V_{IN} = V_{IL} \text{ or } V_{IH}$	$I_{OH} = -8 \text{ mA}$	2.3	1.9	2.1		1.9		
		$I_{OH} = -12 \text{ mA}$	2.7	2.2	2.4		2.2		
		$I_{OH} = -16 \text{ mA}$	3.0	2.4	2.7		2.4		
		$I_{OH} = -24 \text{ mA}$	3.0	2.3	2.5		2.3		
		$I_{OH} = -32 \text{ mA}$	4.5	3.8	4.0		3.8		
VOL	Low-Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 to 5.5			0.1		0.1	V
	VIN = VIH or VOH	$I_{OL} = 8 \text{ mA}$	2.3		0.20	0.3		0.3	
		I <sub>OL</sub> = 12 mA	2.7		0.22	0.4		0.4	
		I <sub>OL</sub> = 16 mA	3.0		0.28	0.4		0.4	
		I <sub>OL</sub> = 24 mA	3.0		0.38	0.55		0.55	
		$I_{OL} = 32 \text{ mA}$	4.5		0.42	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	0 to 5.5			± 0.1		±1.0	μΑ
IOFF	Power Off–Output Leakage Current	V <sub>OUT</sub> = 5.5 V	0			1		10	μΑ
ICC	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

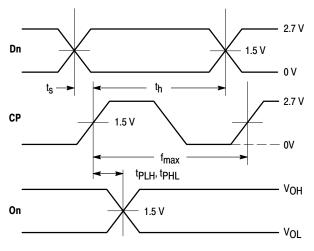
#### AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

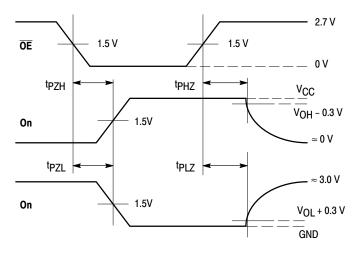
			VCC	-	$T_A = 25^{\circ}C$			$T_A \leq 85^{\circ}C$	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
fMAX	Maximum Clock	$R_L = 500 \text{ M}\Omega, C_L = 50 \text{ pF}$	$2.5 \pm 0.2$				125		MHz
	Frequency		$3.3 \pm 0.3$				150		
			$5.0 \pm 0.5$				175		
<sup>t</sup> plh	Propagation Delay	$R_L = 1 M\Omega$ , $C_L = 15 pF$	$2.5 \pm 0.2$	2.0	3.8	6.5	2.0	7.0	ns
<sup>t</sup> phI	CP to Q	$R_L = 1 M\Omega$ , $C_L = 15 pF$	$3.3 \pm 0.3$	1.5	2.8	4.5	1.4	5.0	
	(Figure 6)	$R_L = 500 \Omega$ , $C_L = 50 pF$		2.0	3.4	5.5	1.6	6.2	
		$R_L = 1 M\Omega$ , $C_L = 15 pF$	$5.0 \pm 0.5$	1.0	2.2	3.5	1.0	3.8	
		$R_L = 500 \Omega, C_L = 50 pF$		1.5	2.6	4.0	1.4	4.7	
t <sub>pzl</sub>	Output Enable Time	$R_L = 250 \Omega, C_L = 50 pF$	$2.5 \pm 0.2$	2.0	3.7	6.0	1.8	6.6	ns
t <sub>pzh</sub>	(Figure 7)		$3.3 \pm 0.3$	1.5	2.8	5.0	1.4	5.3	
			$5.0 \pm 0.5$	1.0	2.2	3.7	1.0	3.9	
tplz	Output Disable Time	R <sub>L</sub> and R <sub>1</sub> = 500 $\Omega$ ,	$2.5 \pm 0.2$	2.0	3.5	6.0	1.8	6.3	ns
<sup>t</sup> phz	(Figure 8)	$C_{L}^{-} = 50 \text{ pF}$	$3.3 \pm 0.3$	1.5	2.8	4.5	1.4	4.7	
			$5.0 \pm 0.5$	1.0	2.3	3.7	1.0	3.9	
ts	Setup Time CP to D	$R_L = 500 \Omega, C_L = 50 pF$	$2.5 \pm 0.2$				2.5		ns
	(Figure 6)		$3.3 \pm 0.3$				2.0		
			$5.0 \pm 0.5$				1.5		
t <sub>H</sub>	Hold Time CP to D	$R_L = 500 \Omega, C_L = 50 pF$	$2.5 \pm 0.2$				1.5		ns
	(Figure 6)		$3.3 \pm 0.3$				1.5		
			$5.0 \pm 0.5$				1.5		
tW	CP Pulse Width	$R_L = 500 \Omega, C_L = 50 pF$	$2.5 \pm 0.2$				3.0		ns
	(Figure 6)		$3.3 \pm 0.3$				2.8		
			$5.0 \pm 0.5$				2.5		

#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 5.5 \text{ V}, V_I = 0 \text{ V or } V_{CC}$	4.0	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.5 \text{ V}, V_O = 0 \text{ V or } V_{CC}$	4.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF
	(Note 6)	10 MHz, $V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	30	

6. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>In</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>In</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

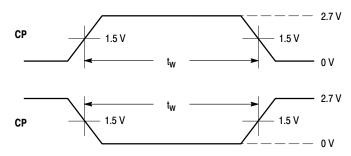




#### WAVEFORM 1 – PROPAGATION DELAYS, SETUP AND HOLD TIMES

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$ 

# WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.5 \text{ ns}$ , 10% to 90%; f = 1 MHz; $t_W = 500 \text{ ns}$

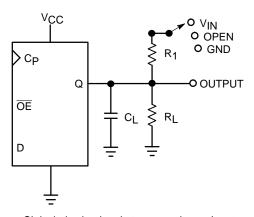


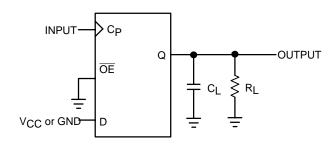
#### **WAVEFORM 3 – PULSE WIDTH**

 $t_R$  =  $t_F$  = 2.5 ns (or fast as required) from 10% to 90%; Output requirements:  $V_{OL} \le$  0.8 V,  $V_{OH} \ge$  2.0 V

Figure 4. AC Waveforms

### **TEST CIRCUITS**





CL includes load and stray capacitance Input

Figure 5.

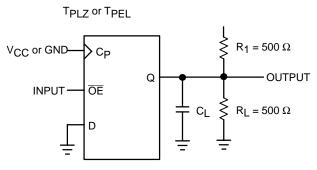


Figure 7.

Figure 6.

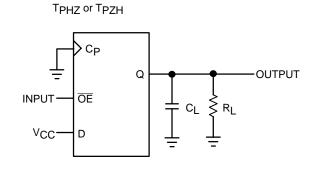


Figure 8.

#### **DEVICE ORDERING INFORMATION**

Device Nomenclature									
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape and Reel Suffix	Package Type	Tape and Reel Size
NL17SZ374DFT2	NL	1	7	SZ	374	DF	T2	SC-88/ SOT-363/ SC70-6	178 mm, 3000 Units

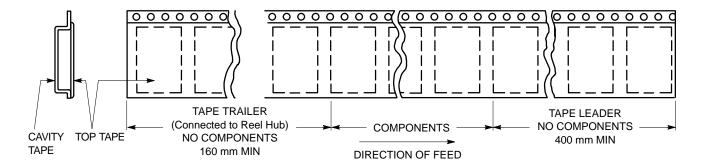


Figure 9. Tape Ends for Finished Goods

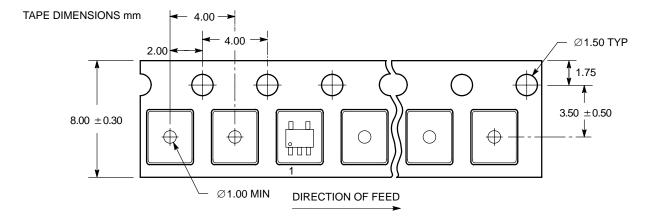


Figure 10. SC-70/SC-88A/SOT-353 DFT2 Reel Configuration/Orientation

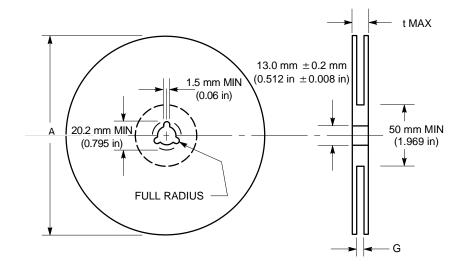


Figure 11. Reel Dimensions

#### **REEL DIMENSIONS**

Tape Size	T and R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7 in)	8.4 mm, + 1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

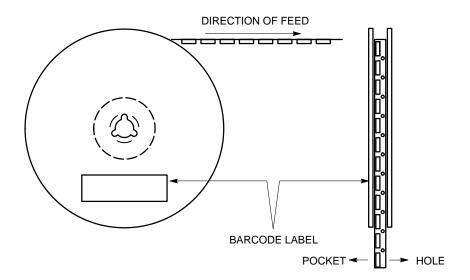
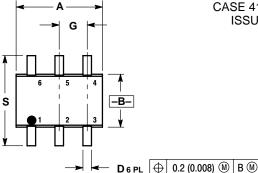


Figure 12. Reel Winding Direction

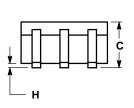
#### PACKAGE DIMENSIONS

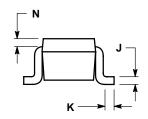
#### SC70-6/SC-88/SOT-363 **DF SUFFIX**

6-LEAD PACKAGE CASE 419B-02 **ISSUE H** 





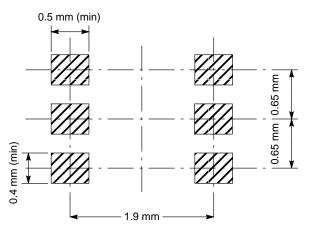




#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIM	IETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.071	0.087	1.80	2.20		
В	0.045	0.053	1.15	1.35		
С	0.031	0.043	0.80	1.10		
D	0.004	0.012	0.10	0.30		
G	0.026	BSC	0.65	BSC		
H		0.004		0.10		
_	0.004	0.010	0.10	0.25		
K	0.004	0.012	0.10	0.30		
N	0.008 REF		0.20	REF		
S	0.079	0.087	2.00	2.20		



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